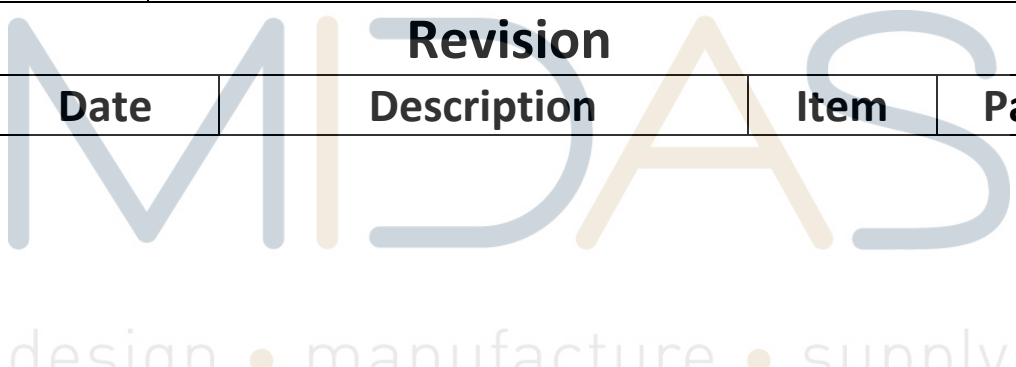
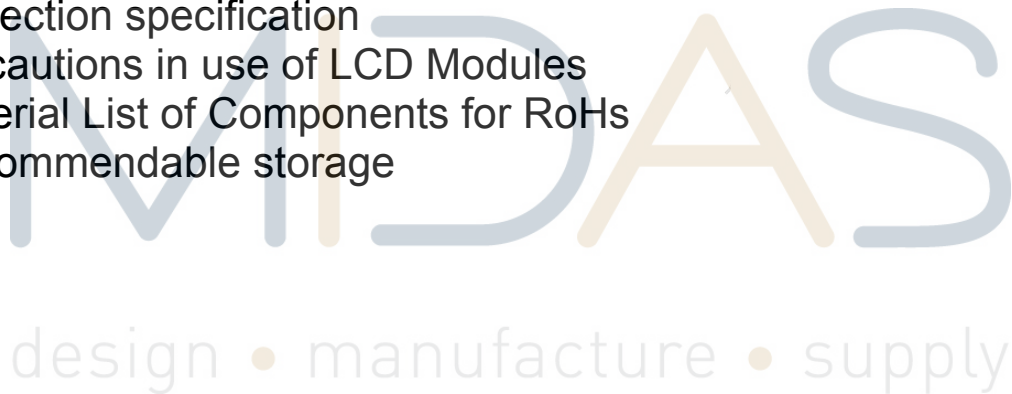


Specification				
Part Number:	MCCOG22405A6W-FPTLWI			
Version:	1			
Date:	30/07/2012			
Revision				
No.	Date	Description	Item	Page
				

Contents

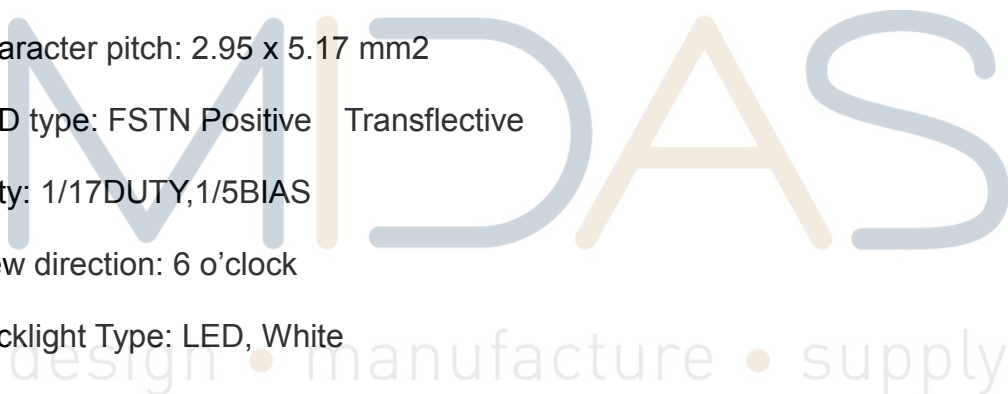
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3. Module Coding System	5
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2. General Specification

The Features of the Module is description as follow:

- Module dimension: 86.2 x 24.7 x 6.0(MAX) mm³
- View area: 72.3 x 11.84 mm²
- Active area: 70.3 x 9.84 mm²
- Number of Characters: 24 characters x 2 Lines
- Dot size: 0.45 x 0.54 mm²
- Dot pitch: 0.50x 0.59 mm²
- Character size: 2.45 x 4.67 mm²
- Character pitch: 2.95 x 5.17 mm²
- LCD type: FSTN Positive Transflective
- Duty: 1/17DUTY,1/5BIAS
- View direction: 6 o'clock
- Backlight Type: LED, White



Midas LCD Part Number System

MC COG 132033 A * 6 W * * - S N T L W * *
1 2 3 4 5 6 7 8 9 - 10 11 12 13 14 15 16

- 1 = **MC:** Midas Components
- 2 = **Blank:** COB (chip on board) **COG:** chip on glass
- 3 = **No of dots** (e.g. 240064 = 240 x 64 dots) (e.g. 21605 = 2 x 16 5mm C.H.)
- 4 = **Series**
- 5 = **Series Variant:** A to Z – see addendum
- 6 = **3:** 3 o'clock **6:** 6 o'clock **9:** 9 o'clock **12:** 12 o'clock
- 7 = **S:** Normal (0 to + 50 deg C) **W:** Wide temp. (-20 to + 70 deg C) **X:** Extended temp (-30 + 80 Deg C)
- 8 = **Character Set**

Blank: Standard (English/Japanese)
C: Chinese Simplified (Graphic Displays only)
CB: Chinese Big 5 (Graphic Displays only)
H: Hebrew
K: European (std) (English/German/French/Greek)
L: English/Japanese (special)
M: European (English/Scandinavian)
R: Cyrillic
W: European (English/Greek)
U: European (English/Scandinavian/Icelandic)

9 = **Bezel Height** (where applicable /available)

	Top of Bezel to Top of PCB	LED Connection Common (via pins 1 and 2) via pins 15+ 16-	Array or Edge Lit
Blank	9.5mm / not applicable	Common	Array
2	8.9 mm	Common	Array
3	7.8 mm	Separate	Array
4	7.8 mm	Common	Array
5	9.5 mm	Separate	Array
6	7 mm	Common	Array
7	7 mm	Separate	Array
8	6.4 mm	Common	Edge
9	6.4 mm	Separate	Edge
A	5.5 mm	Common	Edge
B	5.5 mm	Separate	Edge
D	6.0mm	Separate	Edge
E	5.0mm	Separate	Edge
F	4.7mm	Common	Edge
G	3.7mm	Separate	EL
H	7 mm	Separate	Edge

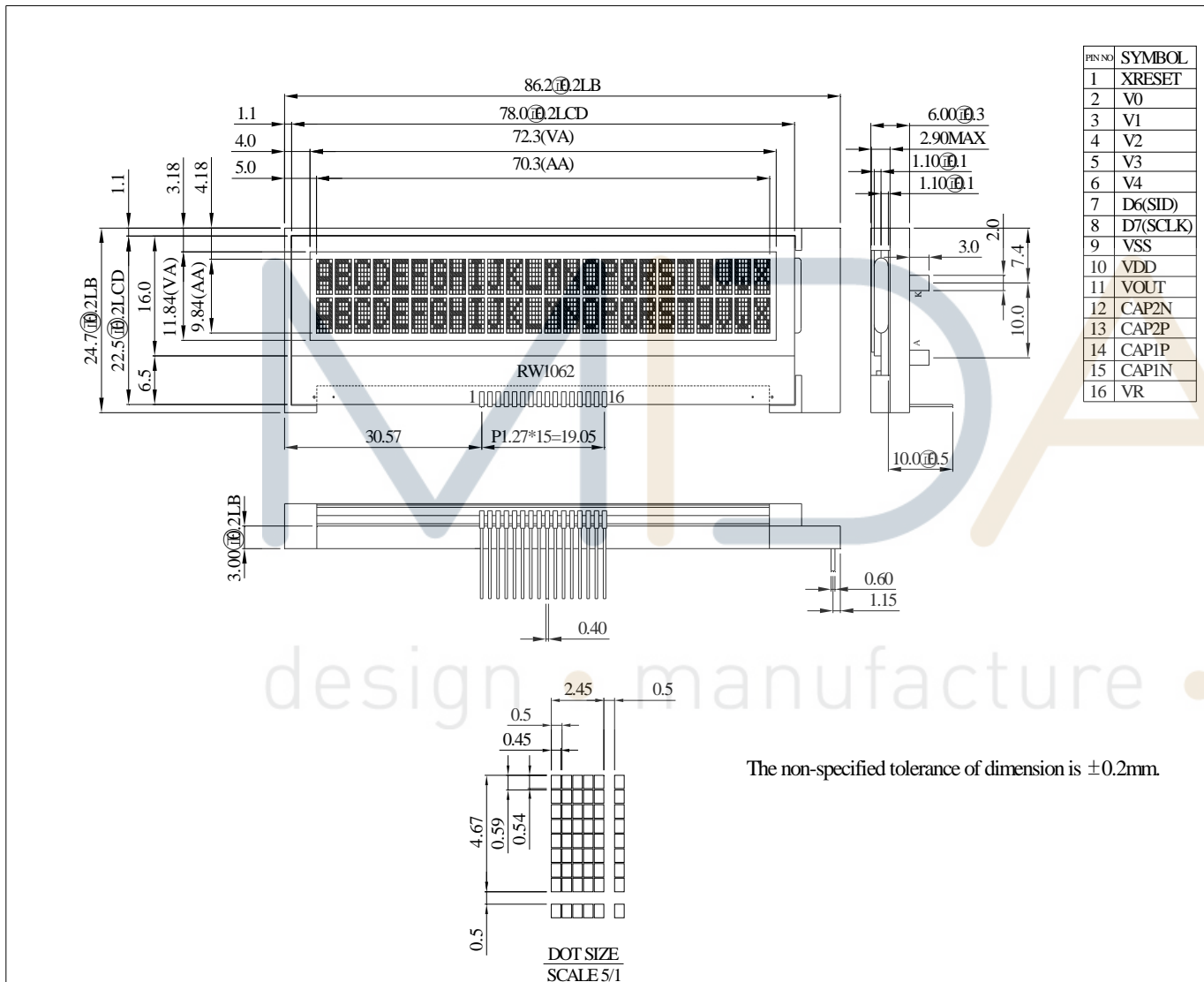
- 10 = **T:** TN **S:** STN **B:** STN Blue **G:** STN Grey **F:** FSTN **F2:** FFSTN **V:** VA (Vertically Aligned)
- 11 = **P:** Positive **N:** Negative
- 12 = **R:** Reflective **M:** Transmissive **T:** Transflective
- 13 = **Backlight:** **Blank:** Reflective **L:** LED
- 14 = **Backlight Colour:** **Y:** Yellow-Green **W:** White **B:** Blue **R:** Red **A:** Amber **O:** Orange **G:** Green **RGB:** R.G.B.
- 15 = **Driver Chip:** **Blank:** Standard **I:** I²C **S:** SPI **T:** Toshiba T6963C **A:** Avant SAP1024B **R:** Raio RA6963
- 16 = **Voltage Variant:** e.g. **3** = 3v

4. Interface Pin Function

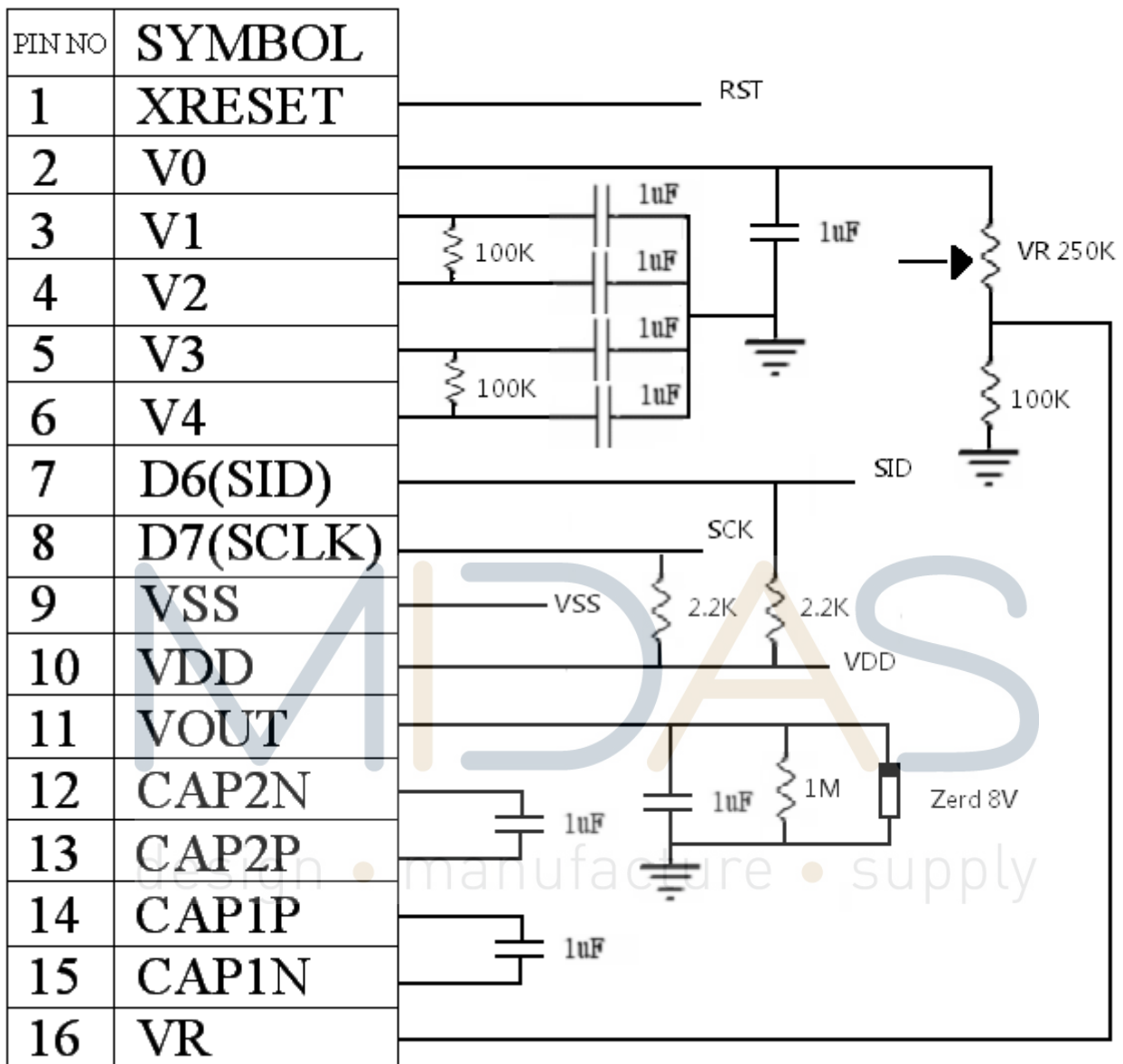
Pin No.	Symbol	Level	Description
1	XRESET		Reset pin, Initialized to Low
2~6	V0~V4		Bias voltage level for LCD driving
7	D6(SID)		Serial input data
8	D7(SCLK)		Serial clock
9	VSS		GND
10	VDD	3.0/5.0	Power supply
11	VOOUT		Voltage converter output voltage
12	CAP2N		External Capacitance input, To use the voltage converter (2 times/ 3times), these pins must be connected to the external capacitance.
13	CAP2P		
14	CAP1P		
15	CAP1N		
16	VR		Reference voltage input to generate V0

design • manufacture • supply

5. Outline Dimension



Application schematic



INITIALIZE:

```
MOV      I2C_CONTROL,#00H    ;WRITE COMMAND
MOV      I2C_DATA,#30H      ;Function Set RE=0
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#30H      ;Function Set RE=0
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#08H      ;DISPLAY OFF
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#06H      ;Entry Mode Set
LCALL   WRITE_CODE
LCALL   DELAY_39uS
LCALL   CGRAM
MOV      I2C_CONTROL,#00H
MOV      I2C_DATA,#34H      ;Function Set RE=1
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#02H      ;Standby Mode Set: (RE = 1)
LCALL   WRITE_CODE          ;NORMAL MODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#06H      ;Entry Mode Set: (RE = 1)
LCALL   WRITE_CODE          ;SEG NORMAL COM REVERSE
LCALL   DELAY_39uS
MOV      I2C_DATA,#16H      ;Booster on, Regulator on, Follower on
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#08H      ;Extended Function Set (RE = 1)
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#08H      ;Extended Function Set (RE = 1)
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_CONTROL,#00H
MOV      I2C_DATA,#30H      ;Function Set RE=0
LCALL   WRITE_CODE
LCALL   DELAY_39uS
MOV      I2C_DATA,#0CH      ;DISPLAY ON,Cursor OFF,Cursor Blink OFF
```



```
LCALL WRITE_CODE
;LCALL DELAY_39uS
MOV     I2C_DATA,#01H     ;CLEAR DISPLAY
LCALL WRITE_CODE
LCALL DELAY_39uS
LCALL DELAY_39uS
RET
```



6. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	°C
Storage Temperature	T_{ST}	-30	—	+80	°C
Input Voltage	V_I	-0.3	—	$V_{DD}+0.3$	V
Supply Voltage For Logic	V_{DD}	-0.3		5.5	V
LCD Driver Voltage	V_O	$V_{SS}+7.0$		$V_{SS}-0.3$	V

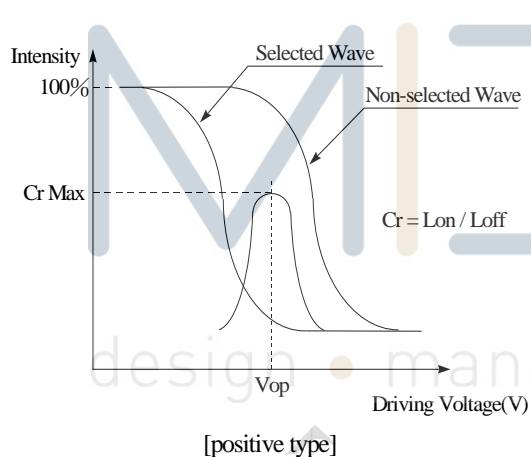
7. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	—	3.0/5.0	—	V
Supply Voltage For LCD	V_O-V_{SS}	$T_a=-20^{\circ}\text{C}$	—	—	—	V
		$T_a=25^{\circ}\text{C}$	—	4.5	—	V
		$T_a=70^{\circ}\text{C}$	—	—	—	V
Input High Volt.	V_{IH}	—	$0.7 V_{DD}$	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	-0.3	—	0.6	V
Output High Volt.	V_{OH}	—	$0.75 V_{DD}$	—	—	V
Output Low Volt.	V_{OL}	—	—	—	$0.2V_{DD}$	V
Supply Current(No include LED Backlight)	I_{DD}	—	—	0.92/ 2.01	—	mA

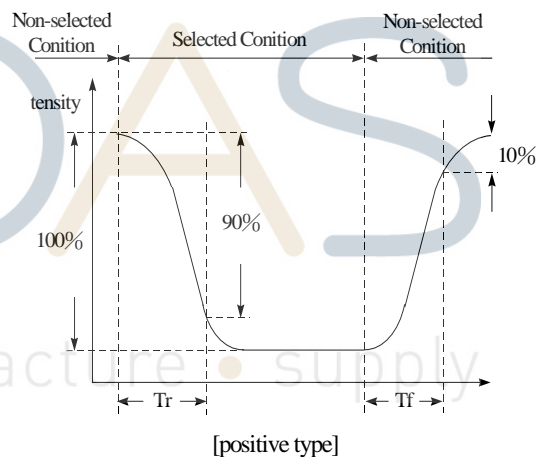
8.Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	$CR \geq 2$	30	—	60	deg
	(H) φ	$CR \geq 2$	-45	—	45	deg
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	200	300	ms
	T fall	—	—	200	300	ms

Definition of Operation Voltage (Vop)



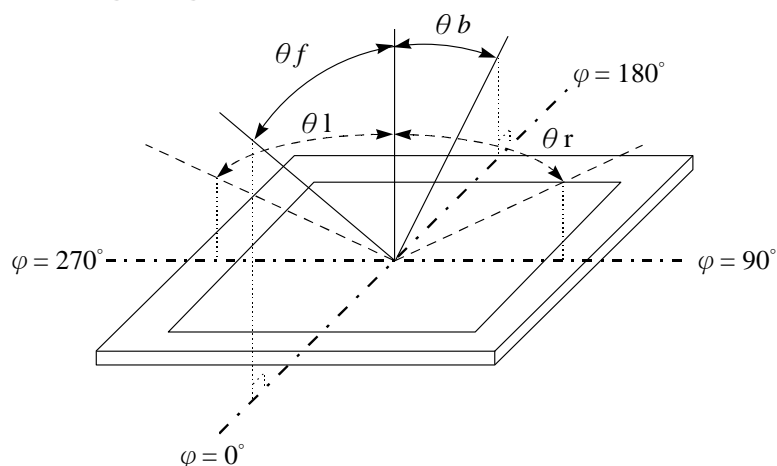
Definition of Response Time (Tr , Tf)



Conditions :

Operating Voltage : Vop Viewing Angle(θ , φ) : 0° , 0°
 Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle($CR \geq 2$)



9. INTERFACE WITH MPU IN BUS MODE

For serial interface data, bus lines (DB6 and DB7) are used. IIC interface

The IIC interface receives and executes the commands sent via the IIC Interface. It also receives RAM

data and sends it to the RAM.

The IIC Interface is for bi-directional, two-line communication between different ICs or modules. Serial data line SDA (DB6) must be connected to a positive supply via a pull-up resistor. Data transfer may be initiated only when the bus is not busy.

* When IIC interface is selected, the INF register must be set to "1".

BIT TRANSFER

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse because changes in the data line at this time will be interpreted as a control signal. Bit transfer is illustrated in Fig.9.1

START AND STOP CONDITIONS

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P). The START and STOP conditions are illustrated in Fig.9.2

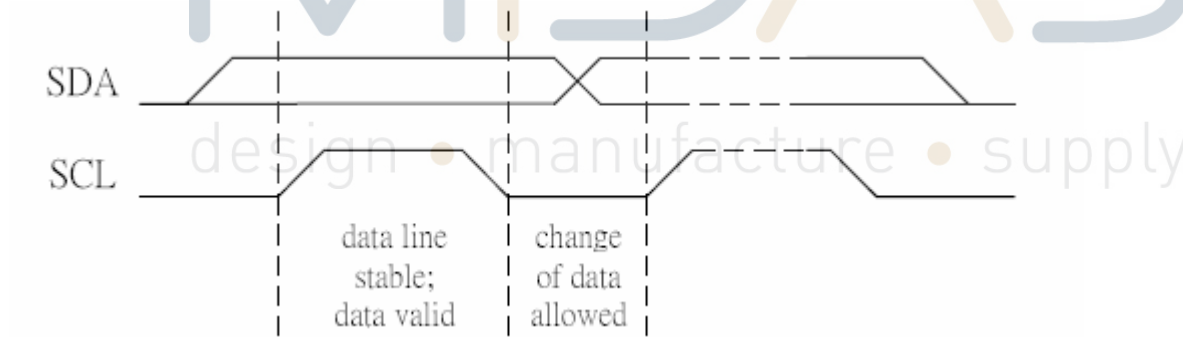


Fig .9.1 Bit transfer

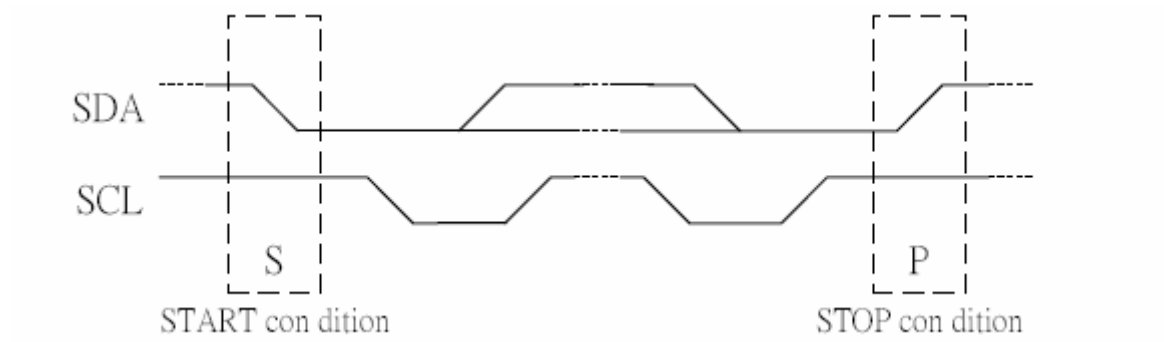


Fig .9.2 Definition of START and STOP conditions

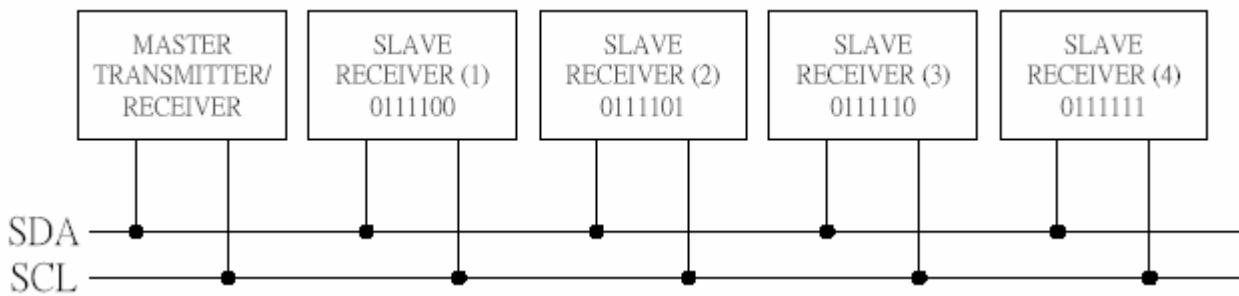


Fig .9.3 System configuration

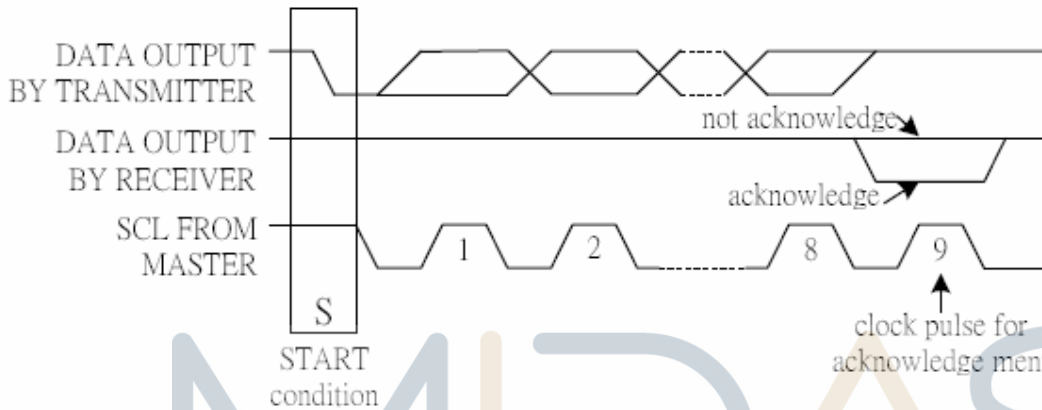


Fig .9.4 Acknowledgement on the 2-line Interface

The system configuration is illustrated in Fig.9.3

- Transmitter: the device, which sends the data to the bus
- Receiver: the device, which receives the data from the bus
- Master: the device, which initiates a transfer, generates clock signals and terminates a transfer
- Slave: the device addressed by a master
- Multi-Master: more than one master can attempt to control the bus at the same time without corrupting the message
- Arbitration: procedure to ensure that, if more than one master simultaneously tries to control the bus, only one is allowed to do so and the message is not corrupted
- Synchronization: procedure to synchronize the clock signals of two or more devices.

ACKNOWLEDGE

Each byte of eight bits is followed by an acknowledge bit. The acknowledge bit is a HIGH signal put on the bus by the transmitter during which time the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an Acknowledge after the reception of each byte. A master receiver must also generate an Acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges must pull-down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the Acknowledge related clock pulse (set-up and hold times must be taken into consideration). A master receiver must signal an end-of-data to the transmitter by not generating an Acknowledge on the last byte that has been clocked out

of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition. Acknowledgement on the IIC Interface is illustrated in Fig.9.4

IIC Interface protocol

The RW1062 supports command, data write addressed slaves on the bus.

Before any data is transmitted on the IIC Interface, the device, which should respond, is addressed first. Four 7-bit slave addresses (0111100, 0111101, 0111110 and 0111111) are reserved for the RW1062. The least significant bit of the slave address is set by connecting the input DB0 and DB1 to either logic 0 (or logic 1 (VDD)).

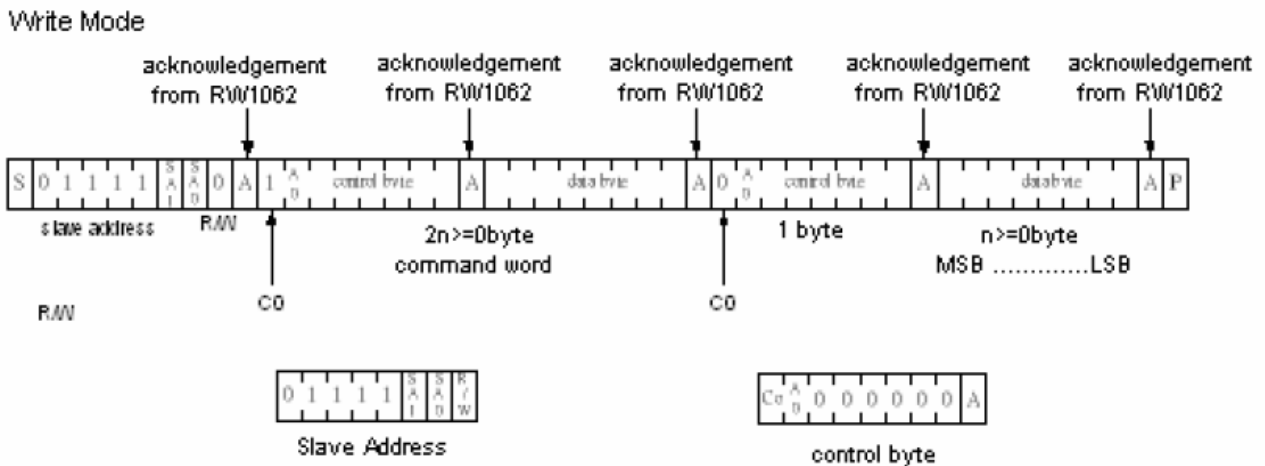
The IIC Interface protocol is illustrated in Fig.9.5

The sequence is initiated with a START condition (S) from the IIC Interface master, which is followed by the slave address. All slaves with the corresponding address acknowledge in parallel, all the others will ignore the IIC Interface transfer. After acknowledgement, one or more command words follow which define the status of the addressed slaves.

A command word consists of a control byte, which defines Co and A0, plus a data byte.

The last control byte is tagged with a cleared most significant bit (i.e. the continuation bit Co).

After a control byte with a cleared Co bit, only data bytes will follow. The state of the A0 bit defines whether the data byte is interpreted as a command or as RAM data. All addressed slaves on the bus also acknowledge the control and data bytes. After the last control byte, depending on the A0 bit setting; either a series of display data bytes or command data bytes may follow. If the A0 bit is set to logic 1, these display bytes are stored in the display RAM at the address specified by the data pointer. The data pointer is automatically updated and the data is directed to the intended RW1062 device. If the A0 bit of the last control byte is set to logic 0, these command bytes will be decoded and the setting of the device will be changed according to the received commands. Only the addressed slave makes the acknowledgement after each byte. At the end of the transmission the IIC interface-bus master issues a STOP condition (P). If no acknowledge is generated by the master after a byte, the driver stops transferring data to the master.



* RW always "0" : RW1062 can only be slave receiver

***SA1,SA0 Always=0**

Fig .9.5 2-line Interface protocol

Co	0	Last control byte to be sent. Only a stream of data bytes is allowed to follow. This stream may only be terminated by s STOP or RE-START condition.
	1	Another control byte will follow the data byte unless a STOP or RE-START condition is received.



Font table

RW1062 Font table (0A-001)

b7~4 b3~0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM [00]			0	1	2	3	4				5	6	7	8	9
0001	CG RAM [01]		!	l	A	a	9				.	7	7	4	9	
0010	CG RAM [02]		"	2	R	b	r				r	4	x	P	0	
0011	CG RAM [03]		#	3	S	c	s				l	0	t	e	e	e
0100	CG RAM [04]		\$	4	T	t	t				.	1	k	k	h	a
0101	CG RAM [05]		%	5	E	e	e				.	0	*	1	0	0
0110	CG RAM [06]		&	6	F	f	f				.	0	1	0	1	0
0111	CG RAM [07]		'	7	G	g	w				.	0	1	0	1	0
1000	CG RAM [00]		(8	H	h	x				.	0	1	0	1	0
1001	CG RAM [01])	9	I	i	w				.	0	1	0	1	0
1010	CG RAM [02]		*	#	J	j	z				.	0	1	0	1	0
1011	CG RAM [03]		+	#	K	k	€				.	0	1	0	1	0
1100	CG RAM [04]		,	<	L	l	l				.	0	1	0	1	0
1101	CG RAM [05]		-	=	M	m	2				.	0	1	0	1	0
1110	CG RAM [06]		.	>	N	n	3				.	0	1	0	1	0
1111	CG RAM [07]		/	?	0	o	e				.	0	1	0	1	0

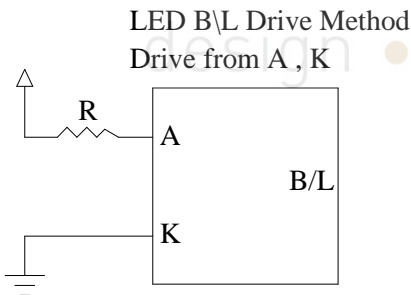
10. Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	I _{LED}	43.2	48	75	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	V _R	—	—	5	V	—
Luminous Intensity (Without LCD)	I _V	570	613	—	CD/M ²	I _{LED} =48mA
LED Life Time	—	—	50K	—	Hr.	I _{LED} ≅ 48mA
Color	White					

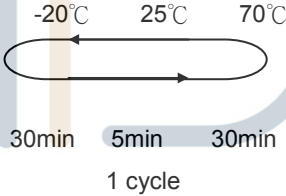
Note: The LED of B/L is drive by current only ; driving voltage is only for reference
 To make driving current in safety area (waste current between minimum and maximum).

Note1 :50K hours is only an estimate for reference.



11. Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

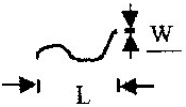
Environmental Test			
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation 	-20°C/70°C 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time	—

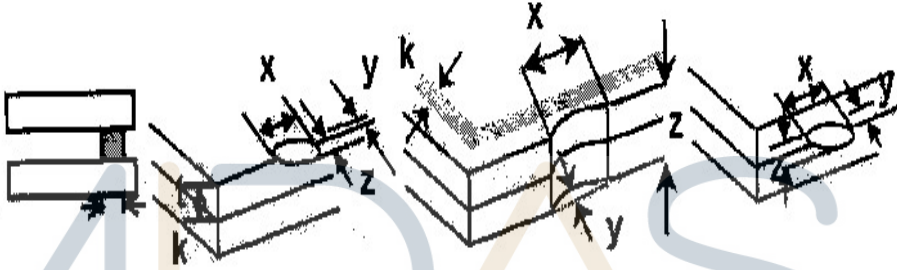
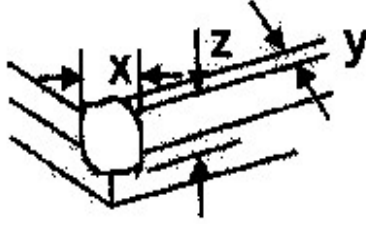
Note1: No dew condensation to be observed.

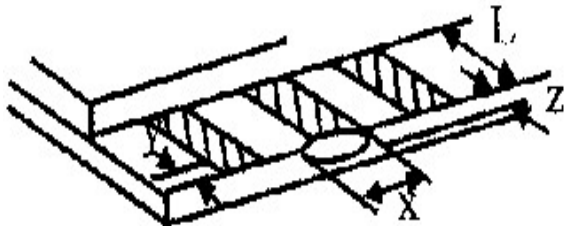
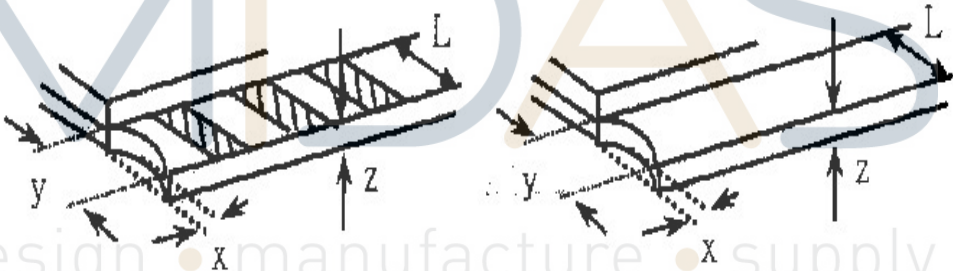
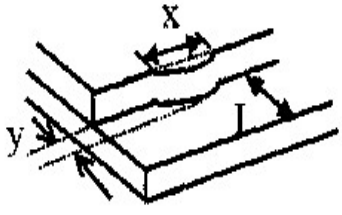
Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

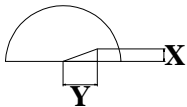
Note3: Vibration test will be conducted to the product itself without putting it in a container.

12. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$	2.5												
		3.2 Line type : (As following drawing)  <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> </tr> </tbody> </table>	Length	Width	Acceptable QTY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$
Length	Width	Acceptable QTY													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>Size Φ</th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total QTY</td> <td>3</td> </tr> </tbody> </table>	Size Φ	Acceptable QTY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total QTY	3	2.5
Size Φ	Acceptable QTY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total QTY	3														

NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:</p> <p>6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="443 1077 1355 1234"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="443 1615 1355 1771"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL																
06	Glass crack	<p>Symbols :</p> <p>x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="336 896 1262 976"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="410 1305 1262 1422"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="745 1668 1262 1749"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

13. Precautions in use of LCD Modules

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don't disassemble the LCM.
4. Don't operate it above the absolute maximum rating.
5. Don't drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Midas have the right to change the passive components
(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Midas have the right to change the PCB Rev.

14. Material List of Components for RoHs

1. Midas Components Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :
 Reflow : 250°C, 30 seconds Max. ;
 Connector soldering wave or hand soldering : 320°C, 10 seconds max.
- (3) Temp. curve of reflow, max. Temp. : 235±5°C ;
 Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

15. Recommendable storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module

LCM Sample Estimate Feedback Sheet

Module Number : _____

1 、 Panel Specification :

1. Panel Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. View Direction :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Numbers of Dots :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. View Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Active Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Operating Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Storage Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Others :	_____	

2 、 Mechanical Specification :

1. PCB Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Frame Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Material of Frame :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Connector Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Fix Hole Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Backlight Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Thickness of PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Height of Frame to PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Height of Module :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

3 、 Relative Hole Size :

1. Pitch of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Hole size of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Mounting Hole size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Mounting Hole Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

4 、 Backlight Specification :

1. B/L Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. B/L Color :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. B/L Driving Voltage (Reference for LED Type) :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. B/L Driving Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Brightness of B/L :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. B/L Solder Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

>> Go to page 2 <<

Module Number : _____

5 、 <u>Electronic Characteristics of Module</u> :		
1.Input Voltage :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2.Supply Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3.Driving Voltage for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4.Contrast for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5.B/L Driving Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6.Negative Voltage Output :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7.Interface Function :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8.LCD Uniformity :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9.ESD test :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10.Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

6 、 Summary :



Sales signature : _____

Customer Signature : _____

Date : / /